

Electronic Patent Application Fee Transmittal

Application Number:	10541586			
Filing Date:	30-Sep-2005			
Title of Invention:	CURING RESIN COMPOSITION, ADHESIVE EPOXY RESIN PASTE, ADHESIVE EPOXY RESIN SHEET, CONDUCTIVE CONNECTION PASTE, CONDUCTIVE CONNECTION SHEET, AND ELECTRONIC COMPONENT JOINED BODY			
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Filer:	Burton A. Amernick/Pam Rollins-Butler			
Attorney Docket Number:	21581-00456-US			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
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Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1510	1510
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Total in USD (\$)				1810